

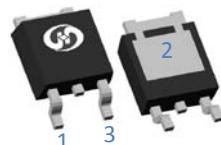
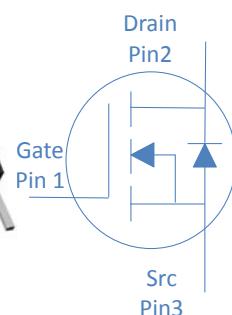
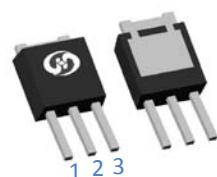
**150V N-Ch Power MOSFET**
**Feature**

- ◇ High Speed Power Switching, logic level
- ◇ Enhanced Body diode dv/dt capability
- ◇ Enhanced Avalanche Ruggedness
- ◇ 100% UIS Tested, 100% Rg Tested
- ◇ Lead Free

**Application**

- ◇ Synchronous Rectification in SMPS
- ◇ Hard Switching and High Speed Circuit
- ◇ Power Tools
- ◇ UPS
- ◇ Motor Control

$V_{DS}$	150	V
$R_{DS(on),typ}$	$V_{GS}=10V$	63 mΩ
$R_{DS(on),typ}$	$V_{GS}=4.5V$	72 mΩ
$I_D$		18 A

**TO-252**

**TO-251**


Part Number	Package	Marking
HGD750N15ML	TO-252	GD750N15ML
HGI750N15ML	TO-251	GI750N15ML

**Absolute Maximum Ratings at  $T_j=25^\circ C$  (unless otherwise specified)**

Parameter	Symbol	Conditions	Value	Unit
Continuous Drain Current (Silicon Limited)	$I_D$	$T_C=25^\circ C$	18	A
		$T_C=100^\circ C$	13	
Drain to Source Voltage	$V_{DS}$	-	150	V
Gate to Source Voltage	$V_{GS}$	-	$\pm 20$	V
Pulsed Drain Current	$I_{DM}$	-	40	A
Avalanche Energy, Single Pulse	$E_{AS}$	$L=0.3mH, T_C=25^\circ C$	3.75	mJ
Power Dissipation	$P_D$	$T_C=25^\circ C$	60	W
Operating and Storage Temperature	$T_J, T_{stg}$	-	-55 to 175	°C

**Absolute Maximum Ratings**

Parameter	Symbol	Max	Unit
Thermal Resistance Junction-Case	$R_{eJC}$	2.5	°C/W
Thermal Resistance Junction-Ambient	$R_{eJA}$	60	°C/W

**Electrical Characteristics at  $T_j=25^\circ\text{C}$  (unless otherwise specified)**
**Static Characteristics**

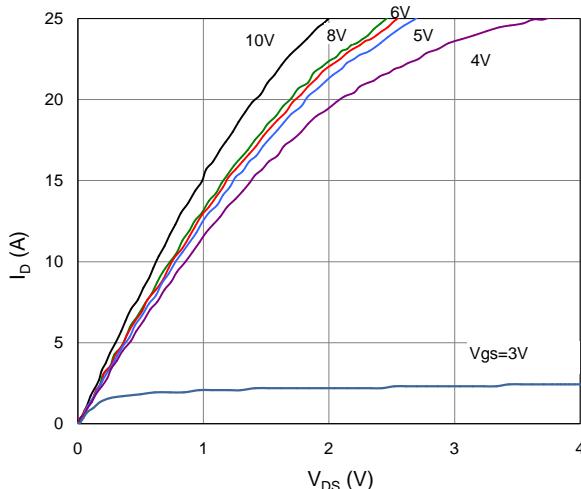
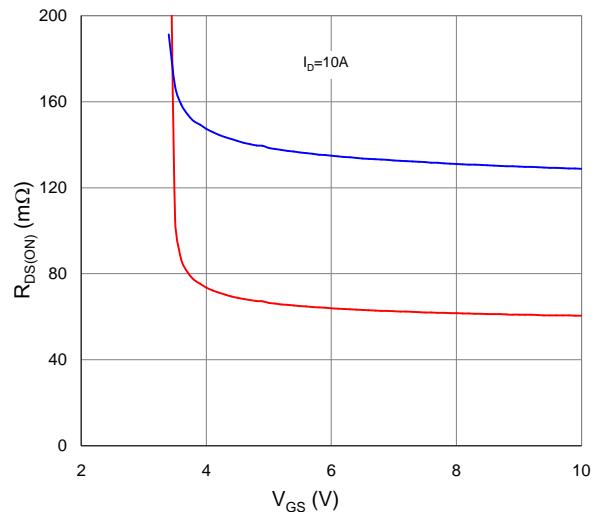
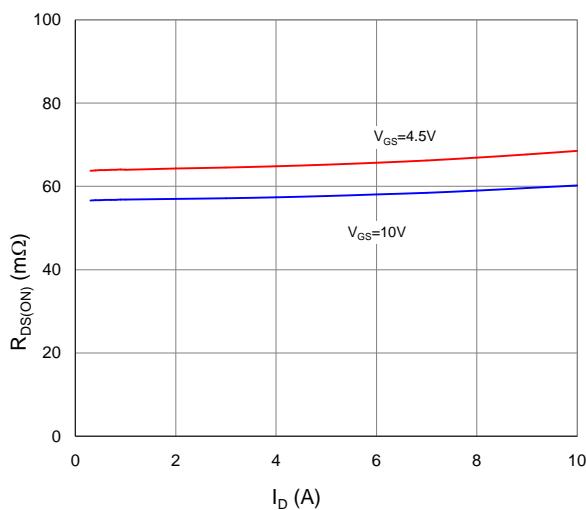
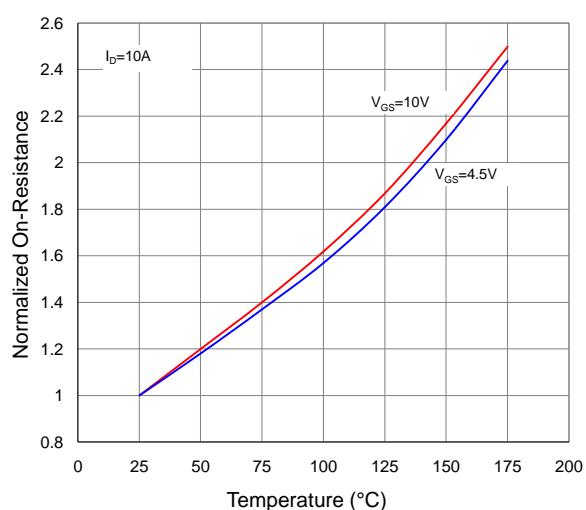
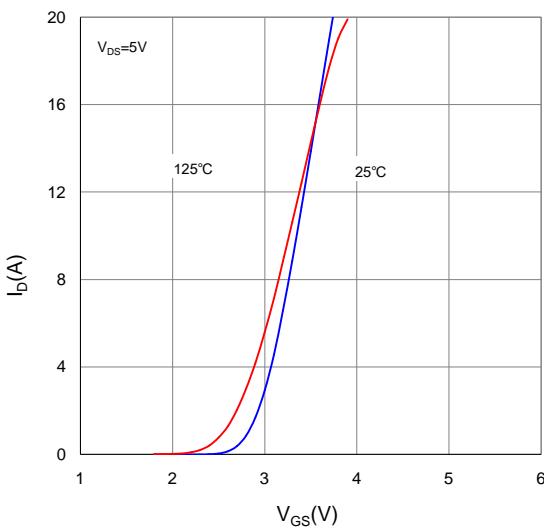
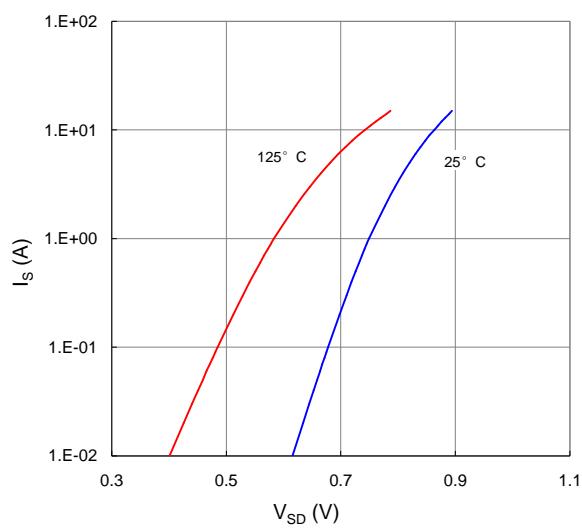
Parameter	Symbol	Conditions	Value			Unit
			min	typ	max	
Drain to Source Breakdown Voltage	$V_{(\text{BR})\text{DSS}}$	$V_{\text{GS}}=0\text{V}, I_D=250\mu\text{A}$	150	-	-	V
Gate Threshold Voltage	$V_{\text{GS}(\text{th})}$	$V_{\text{GS}}=V_{\text{DS}}, I_D=250\mu\text{A}$	1	2	3	
Zero Gate Voltage Drain Current	$I_{\text{DSS}}$	$V_{\text{GS}}=0\text{V}, V_{\text{DS}}=150\text{V}, T_j=25^\circ\text{C}$	-	-	1	$\mu\text{A}$
		$V_{\text{GS}}=0\text{V}, V_{\text{DS}}=150\text{V}, T_j=100^\circ\text{C}$	-	-	100	
Gate to Source Leakage Current	$I_{\text{GSS}}$	$V_{\text{GS}}=\pm20\text{V}, V_{\text{DS}}=0\text{V}$	-	-	$\pm100$	nA
Drain to Source on Resistance	$R_{\text{DS}(\text{on})}$	$V_{\text{GS}}=10\text{V}, I_D=10\text{A}$	-	63	75	$\text{m}\Omega$
		$V_{\text{GS}}=4.5\text{V}, I_D=8\text{A}$	-	72	88	
Transconductance	$g_{\text{fs}}$	$V_{\text{DS}}=5\text{V}, I_D=10\text{A}$	-	23	-	S
Gate Resistance	$R_G$	$V_{\text{GS}}=0\text{V}, V_{\text{DS}} \text{ Open}, f=1\text{MHz}$	-	5.0	-	$\Omega$

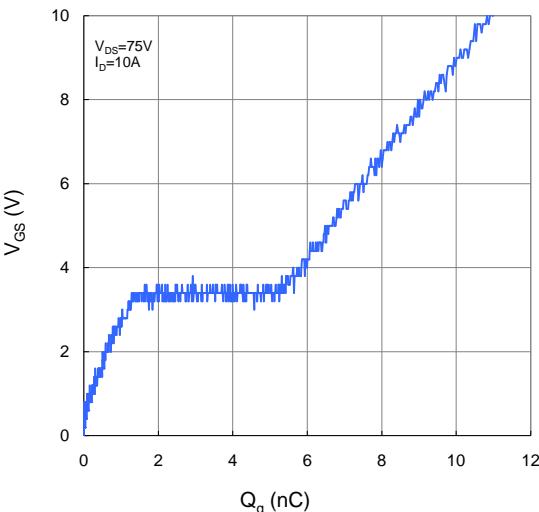
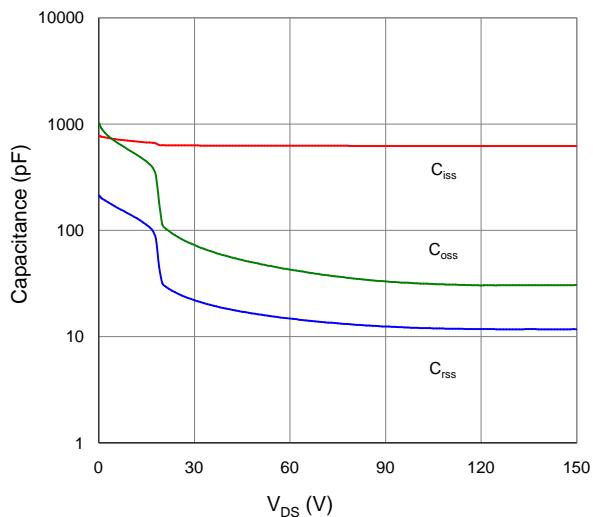
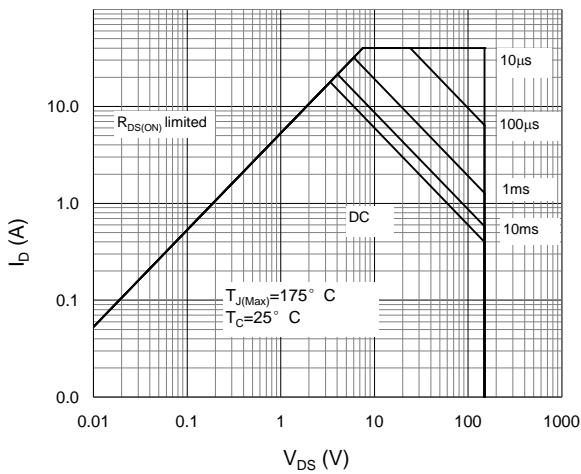
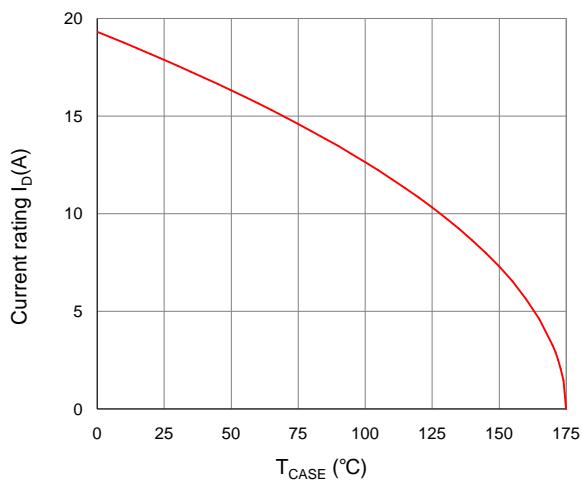
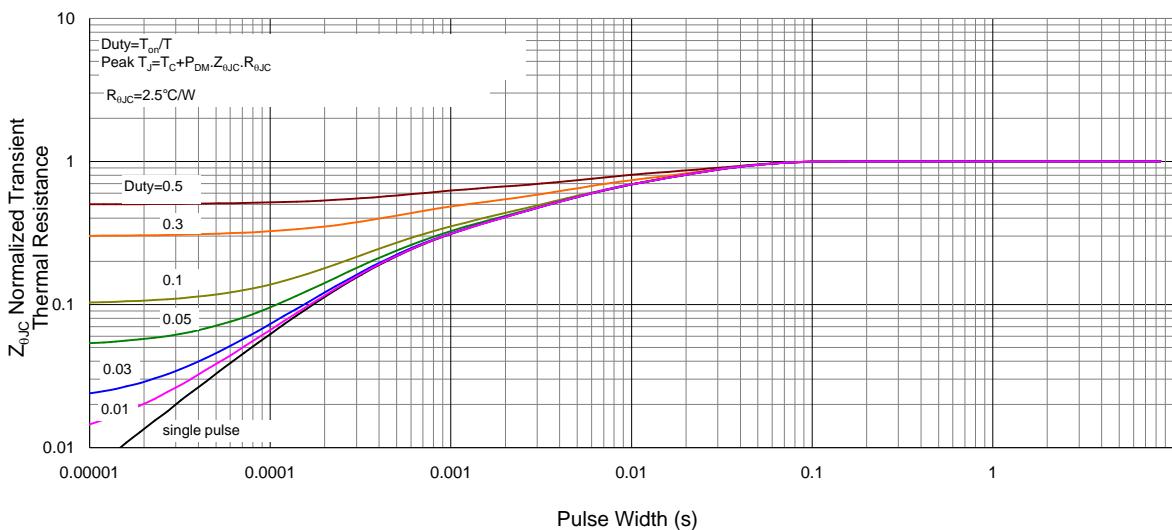
**Dynamic Characteristics**

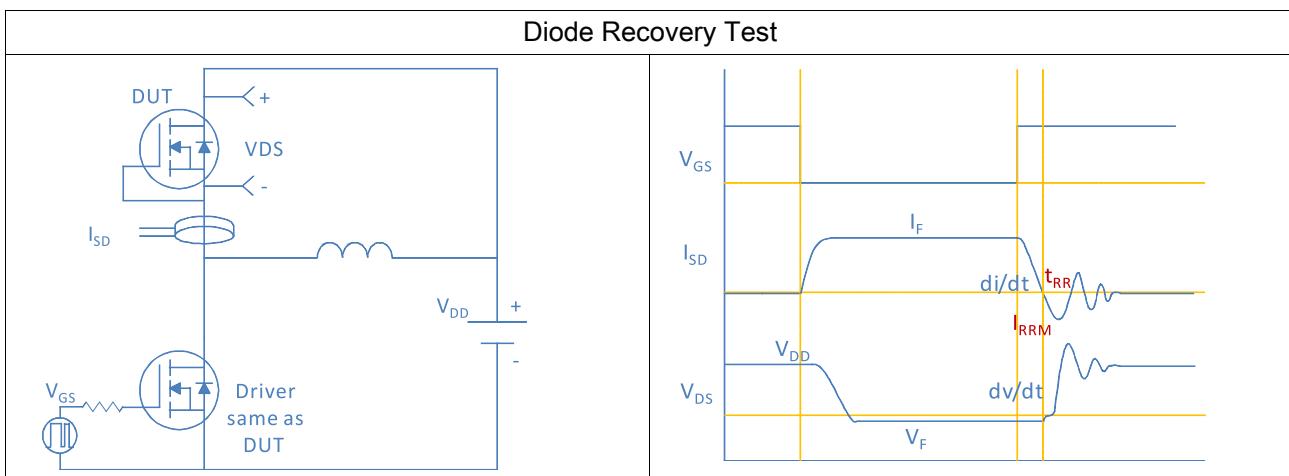
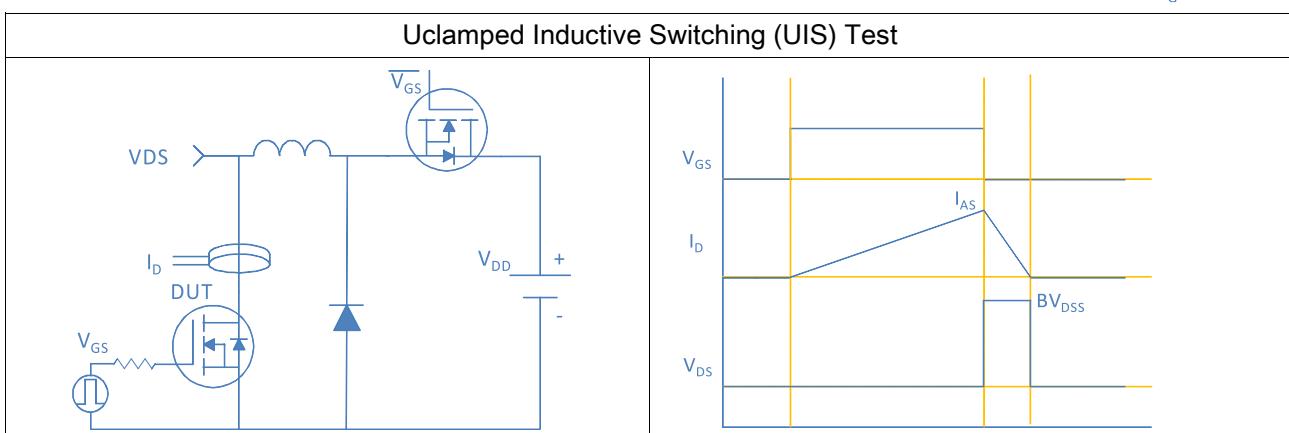
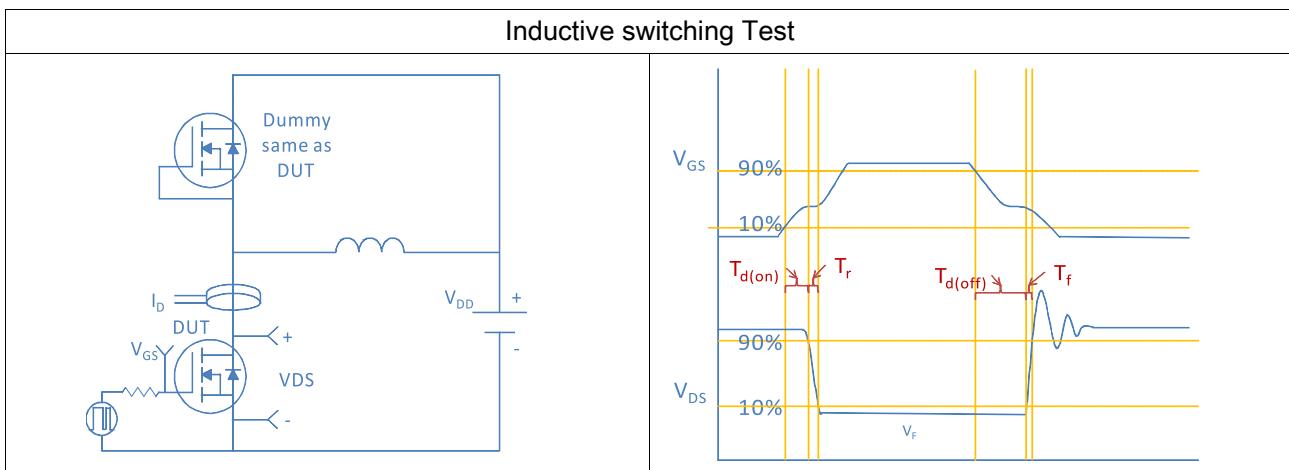
Input Capacitance	$C_{\text{iss}}$	$V_{\text{GS}}=0\text{V}, V_{\text{DS}}=75\text{V}, f=1\text{MHz}$	-	625	-	pF
Output Capacitance	$C_{\text{oss}}$		-	37	-	
Reverse Transfer Capacitance	$C_{\text{rss}}$		-	13	-	
Total Gate Charge	$Q_g$	$V_{\text{DD}}=75\text{V}, I_D=10\text{A}, V_{\text{GS}}=10\text{V}$	-	11	-	nC
Gate to Source Charge	$Q_{\text{gs}}$		-	1.2	-	
Gate to Drain (Miller) Charge	$Q_{\text{gd}}$		-	4	-	
Turn on Delay Time	$t_{\text{d}(\text{on})}$		-	10	-	
Rise time	$t_r$	$V_{\text{DD}}=75\text{V}, I_D=10\text{A}, V_{\text{GS}}=10\text{V}, R_G=10\Omega,$	-	6	-	ns
Turn off Delay Time	$t_{\text{d}(\text{off})}$		-	15	-	
Fall Time	$t_f$		-	4	-	

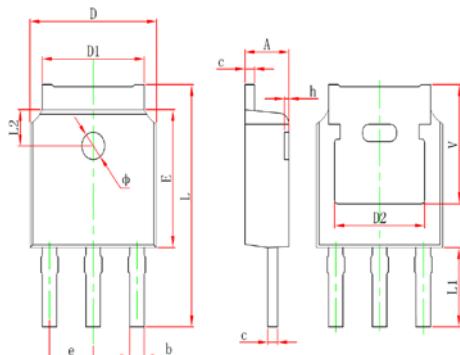
**Reverse Diode Characteristics**

Diode Forward Voltage	$V_{\text{SD}}$	$V_{\text{GS}}=0\text{V}, I_F=10\text{A}$	-	0.9	1.2	V
Reverse Recovery Time	$t_{\text{rr}}$	$V_R=75\text{V}, I_F=10\text{A}, dI_F/dt=100\text{A}/\mu\text{s}$	-	55	-	ns
Reverse Recovery Charge	$Q_{\text{rr}}$		-	124	-	nC

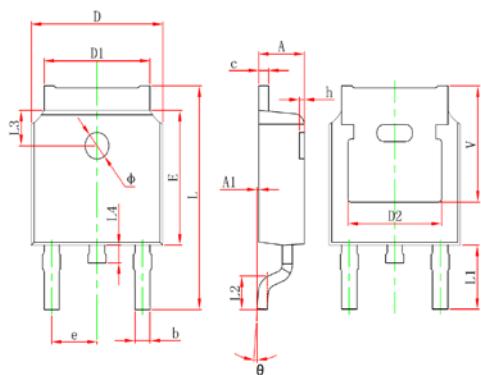
**Fig 1. Typical Output Characteristics**

**Figure 2. On-Resistance vs. Gate-Source Voltage**

**Figure 3. On-Resistance vs. Drain Current and Gate Voltage**

**Figure 4. Normalized On-Resistance vs. Junction Temperature**

**Figure 5. Typical Transfer Characteristics**

**Figure 6. Typical Source-Drain Diode Forward Voltage**


**Figure 7. Typical Gate-Charge vs. Gate-to-Source Voltage**

**Figure 8. Typical Capacitance vs. Drain-to-Source Voltage**

**Figure 9. Maximum Safe Operating Area**

**Figure 10. Maximum Drain Current vs. Case Temperature**

**Figure 11. Normalized Maximum Transient Thermal Impedance, Junction-to-Case**




**Package Outline**
**TO-251, 3 leads**


Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	2.200	2.400	0.087	0.094
b	0.660	0.860	0.026	0.034
c	0.460	0.580	0.018	0.023
D	6.500	6.700	0.256	0.264
D1	5.100	5.460	0.201	0.215
D2	4.830 REF.		0.190 REF.	
E	6.000	6.200	0.236	0.244
e	2.186	2.386	0.086	0.094
L	10.400	11.000	0.409	0.433
L1	3.500 REF.		0.138 REF.	
L2	1.600 REF.		0.063 REF.	
Φ	1.100	1.300	0.043	0.051
h	0.000	0.300	0.000	0.012
V	5.350 REF.		0.211 REF.	

**TO-252, 2 leads**


Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	2.200	2.400	0.087	0.094
A1	0.000	0.127	0.000	0.005
b	0.660	0.860	0.026	0.034
c	0.460	0.580	0.018	0.023
D	6.500	6.700	0.256	0.264
D1	5.100	5.460	0.201	0.215
D2	4.830 REF.		0.190 REF.	
E	6.000	6.200	0.236	0.244
e	2.186	2.386	0.086	0.094
L	9.800	10.400	0.386	0.409
L1	2.900 REF.		0.114 REF.	
L2	1.400	1.700	0.055	0.067
L3	1.600 REF.		0.063 REF.	
L4	0.600	1.000	0.024	0.039
Φ	1.100	1.300	0.043	0.051
θ	0°	8°	0°	8°
h	0.000	0.300	0.000	0.012
V	5.350 REF.		0.211 REF.	